

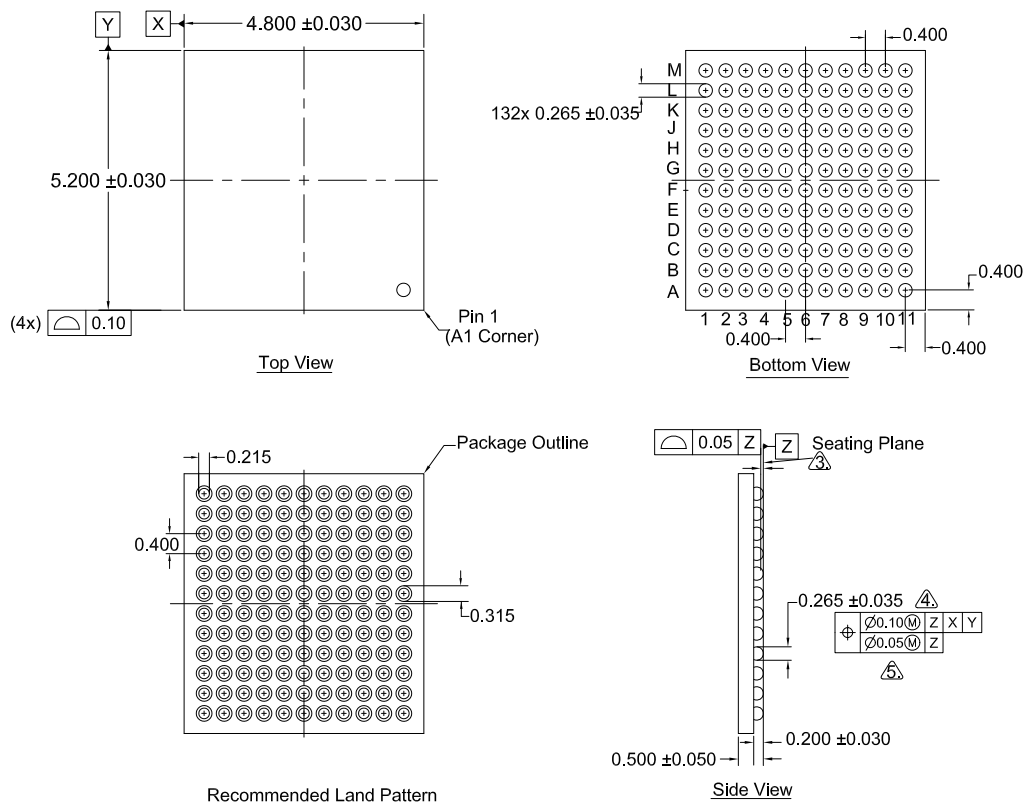
Plastic Packages for Integrated Circuits

Package Outline Drawing

W11x12.132

132 Ball Wafer Level Chip Scale Package (WLCSP 0.4mm Pitch)

Rev 0, 6/2021



Notes:

- All dimensions are in millimeters.
- Dimensions and tolerances per ASMEY 14.5-1994
- Primary datum Z and seating plane are defined by the spherical crowns of the bump.
- Dimension is measured at the maximum bump diameter parallel to primary datum Z .
- Bump position designation per JESD 95-1, SPP-010.
- NSMD refers to non-solder mask defined pad design per TB451.